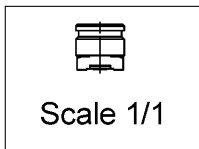
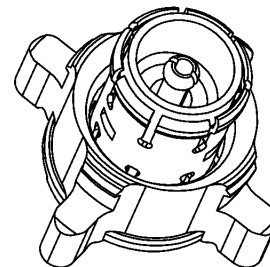
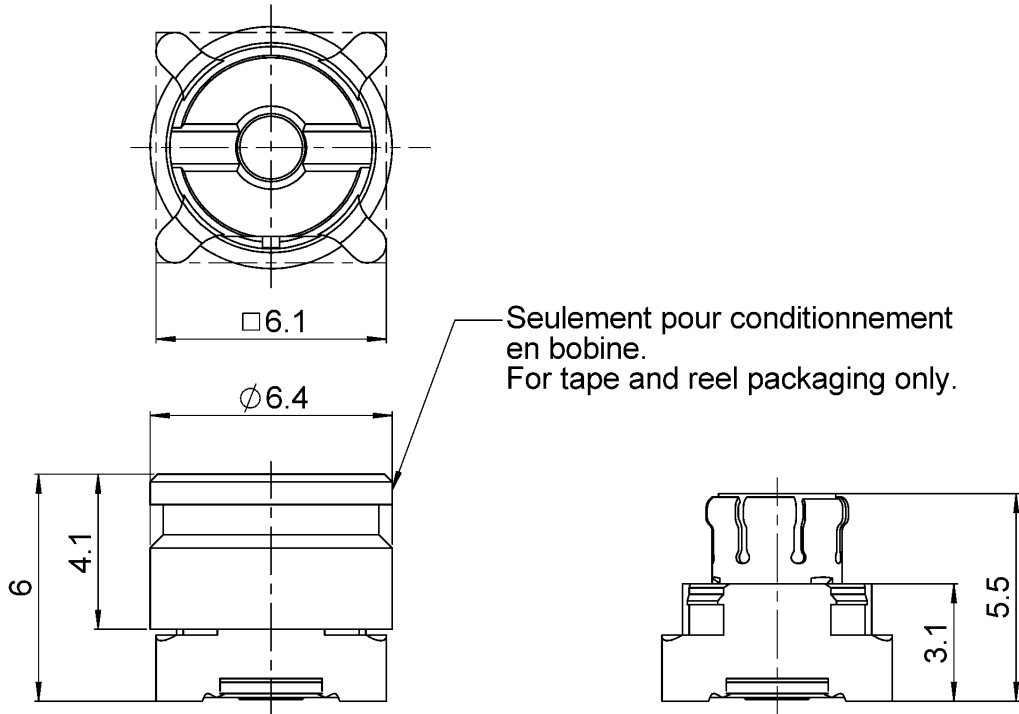
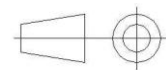


PAGE 1/5	ISSUE 25-01-16D	SERIES MMBX	PART NUMBER R223434800
----------	-----------------	--------------------	-------------------------------



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
Body	BERYLLIUM COPPER; BRASS	NPGR
Center contact	BERYLLIUM COPPER; BRASS	NPGR
Outer contact	-	
Insulator	LIQUID CRYSTAL POLYMER	
Gasket		
Others parts	PTFE	
-	-	-
-	-	-

PAGE 2/5	ISSUE 25-01-16D	SERIES MMBX	PART NUMBER R223434800
----------	------------------------	--------------------	-------------------------------

PACKAGING

Standard	Unit	Other
750	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω
Frequency		0-12.4	GHz
VSWR	1.065*	+	0.0000 x F(GHz) Maxi
Insertion loss		0.12	√F(GHz) dB Maxi
RF leakage	- (100**	- F(GHz)) dB Maxi
Voltage rating		330	Veff Maxi
Dielectric withstanding voltage		1000	Veff mini
Insulation resistance		1000	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention			
Axial force – Mating End		10	N mini
Axial force – Opposite end		10	N mini
Torque		NA	N.cm mini
Recommended torque			
Mating		NA	N.cm
Panel nut		NA	N.cm
Mating life		500	Cycles mini
Weight		0.5440	g

ENVIRONMENTAL

Operating temperature	-55/+155	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:

***to 2GHz (1.106 --- 2 to 6GHz)**
****Interface only, up to 2.5GHz**

PAGE 3/5	ISSUE 25-01-16D	SERIES MMBX	PART NUMBER R223434800
----------	-----------------	-------------	------------------------

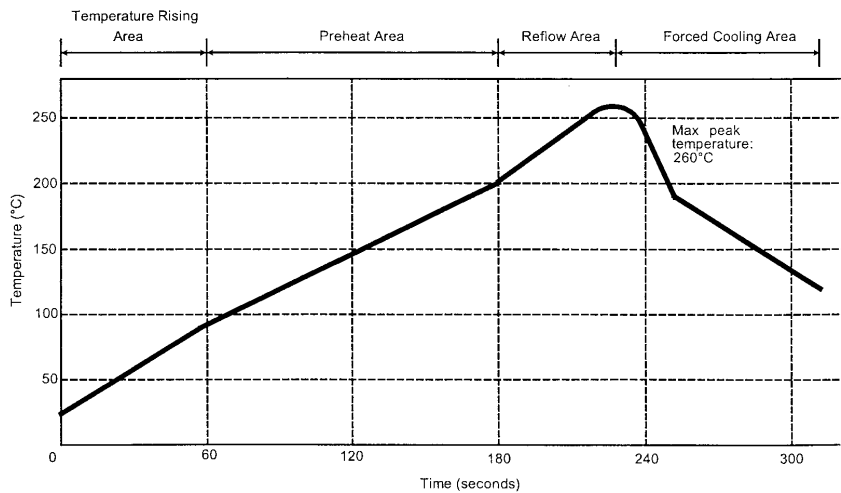
SOLDER PROCEDURE OF MMBX RECEPTACLE IN INDUSTRIAL ENVIRONMENT

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application.
We recommend a low residue flux.
We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

A video camera is recommended for positioning of the component.

Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven.
Below please find, the typical profile to use.
4. The cleaning of printed circuit boards is not obliged.
5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE

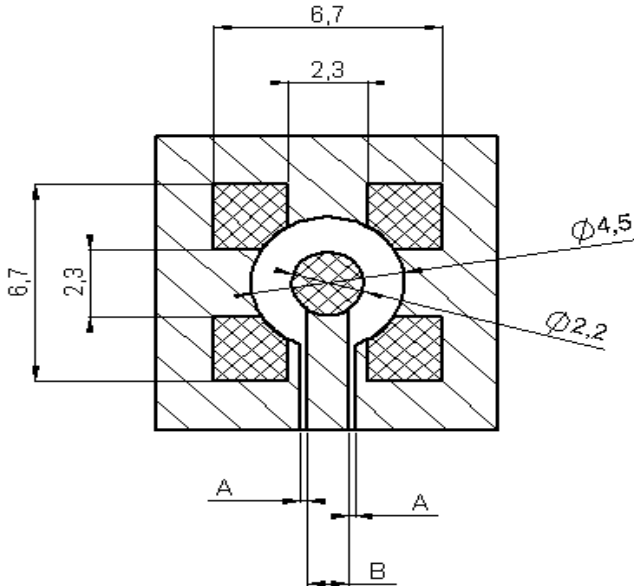


Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

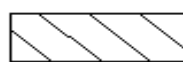
PAGE 4/5	ISSUE 25-01-16D	SERIES MMBX	PART NUMBER R223434800
----------	-----------------	-------------	------------------------

MMBX SERIES INFORMATIONS

PCB



COPLANAR LINE
 Pattern and signal are on the same side
 The material of PCB is epoxy resin (FR4)
 . (Er = 4.6)
 The solder resist should be printed



Pattern



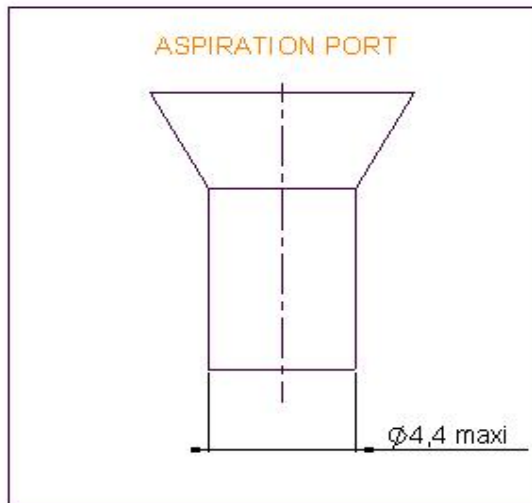
Land for solder paste

APPLICATION 75Ω
 WITH B = 0,55mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,350
1,0	0,360
1,2	0,365
1,6	0,375

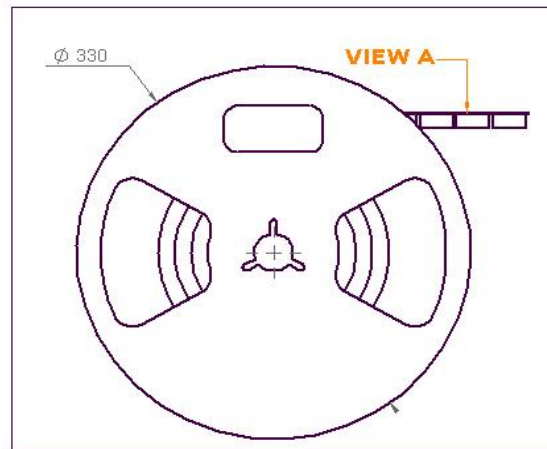
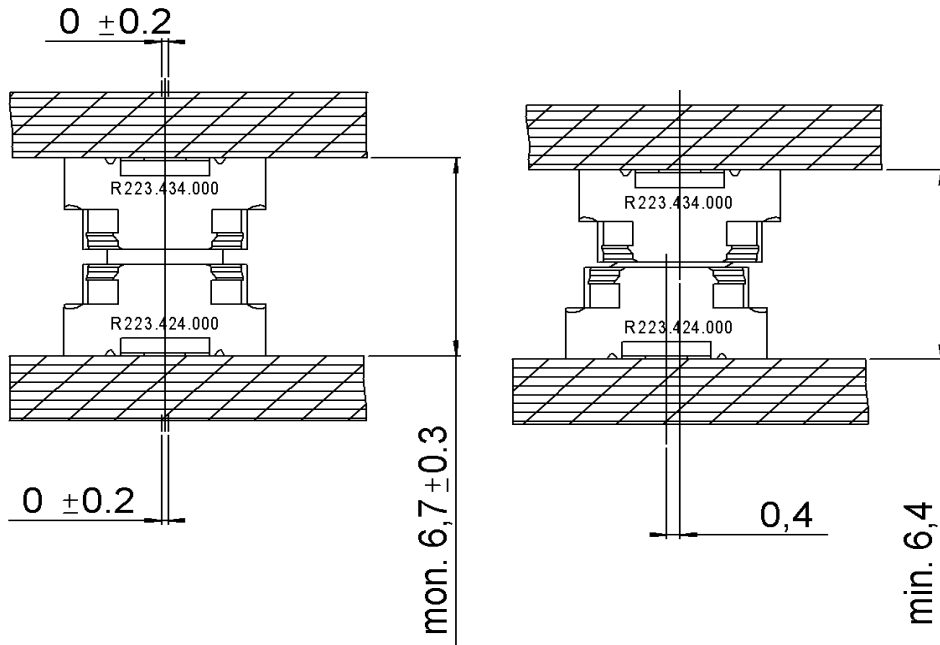
APPLICATION 50Ω
 WITH B = 1,2mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,190
1,0	0,200
1,2	0,205
1,6	0,210



PAGE 5/5	ISSUE 25-01-16D	SERIES MMBX	PART NUMBER R223434800
----------	-----------------	-------------	------------------------

MMBX SERIES INFORMATIONS



A VIEW

